

Application Data Sheet

Application Information

Application Type:: Regular
Subject Matter:: Utility
Title:: Recessed-Bond Semiconductor Package
Substrate
Attorney Docket Number:: TI-35932 (1962-07400)
Suggested Drawing Figure:: 1
Total Drawing Sheets:: 4
Small Entity?: No

Applicant Information

Applicant Authority type:: Inventor
Primary Citizenship Country:: Philippines
Status:: Full Capacity
Given Name:: Edgardo R.
Family Name:: HORTALEZA
City of Residence:: Garland
State or Province of Residence:: TX
Country of Residence:: US
Street of mailing address:: 706 Yaupon Drive
City of mailing address:: Garland
State or Province of
mailing address:: TX
Country of mailing address:: US
Postal or Zip Code of
mailing address:: 75044

Applicant Authority type:: Inventor
Primary Citizenship Country:: US
Status:: Full Capacity
Given Name:: Gregory E.
Family Name:: HOWARD

City of Residence:: Dallas
 State or Province of Residence:: TX
 Country of Residence:: US
 Street of mailing address:: 3554 Waldorf Drive
 City of mailing address:: Dallas
 State or Province of
 mailing address:: TX
 Country of mailing address:: US
 Postal or Zip Code of
 mailing address:: 75229

Correspondence Information

Correspondence Customer Number:: 23494

Representative Information

Representative Customer Number:: 23494

DOMESTIC PRIORITY INFORMATION

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	Non-Provisional of	60/456,708	03/21/03

Assignee Information

Assignee name:: Texas Instruments Incorporated
 Street of mailing address:: P.O. Box 655474, MS 3999
 City of mailing address:: Dallas
 State or Province of
 mailing address:: TX
 Country of mailing
 address:: US
 Postal or Zip Code of
 mailing address:: 75265